U.S. Department of Commerce, Patent and Trademark Office	Atty. Docket No.	Serial No.
	M-15302-1P US	10/798,540
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Applicant(s)	
(Use several sheets if necessary)	Savastiouk et al.	
	Filing Date	Group
	March 10, 2004	2812

U.S. Patent Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
KL	AA	6,322,903	Nov. 2001	Siniaguine et al.			
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						

Foreign Patent Documents

							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
	AK							
	AL							
	AM							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

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KL	AA	2002/0048916	25 Apr. 2002	Yanagida			
	AB	6,175,158	16 Jan. 2001	Degani et al.			
	AC	2003/0080437	1 May 2003	Gonzalez et al.			
	AD	6,661,088	9 Dec. 2003	Yoda et al.			
	AE	2002/0036340	28 Mar. 2002	Matsuo et al.			
	AF	2003/0047798	13 Mar. 2003	Halahan			
	AG	2002/0074637	20 Jun. 2002	McFarland			
	AH	2002/0175421	28 Nov. 2002	Kimura			
	AI	2003/0116859	26 Jun. 2003	Hashimoto			
KL	AJ	6,322,903	27 Nov. 2001	Siniaguine et al.			

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KL	AK	195 31 158 A1	27 Feb. 1997	DE			X	
KL	AL	08-236579	13 Sept. 1996	JP			X	
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KL	AN	"Solving Soldering Hierarchy Problems by Metallurgy and Design" IBM Technical Disclosure Bulletin, IBM Corp. New York, US, vol. 33, no. 8, January 1991, pages 298-299, XP000106967, ISSN: 0018-8689

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KL	AA	5,391,514	Feb. 1995	Gall et al.			
KL	AB	6,903,443	Jun. 2005	Farnworth et al.			
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	AI						

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KL	AA	2003/0199123	23 Oct. 2003	Siniaguine			
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	AE	2002/0074637	20 Jun. 2002	McFarland			
	AF	2002/0175421	28 Nov. 2002	Kimura			
	AG	2003/0080437	1 May 2003	Gonzalez et al.			
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		Document	Date	Country	Class	Subclass	Yes	No
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	AL	Ekstrom; Bjorn "Thin Film Silicon Substrates For Lead Frame Packages" Advancing Microelectronics – May/June 2003, pages 6-7.
	AM	Gilleo, Ken "Substrates for Flip Chips" "Flip Chips Technology" in Area Array Packaging Handbook – Manufacturing and Assembly; K Gillio, Editor; The McGraw-Hill Companies, Inc., New York, NY.
	AN	Maiwald, Werner "Soldering SMD's Without Solder Paste" http://www.midwestpcb.com/sales/Kehoe/maiwald.htm.
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	AQ	Sperling, Ed; Electronic News, 9/17/2003.
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	AZ	Wang, Tie; Tung, Francisca; Foo, Louis; and Dutta, Vivek "Studies on A Novel Flip-Chip Interconnect Structure – Pillar Bump" Advanpack Solutions Pte Ltd, 2001 IEEE, 2001 Electronic Components and Technology Conference.
	BA	United States Patent Application No. 10/739,707, entitled "Packaging Substrates For Integrated Circuits and Soldering Methods," Filed on December 17, 2003; Attorney Docket No.: M-15278 US.
	BB	"Technical Data Sheet: No-Clean Pin-Probe Testable Solder Paste: NC253" www.aimsolder.com.
KL	BC	Zama, Satoru; Baldwin, Daniel F; Hikami, Toshiya; Murata, Hideaki "Flip Chip Interconnect Systems Using Wire Stud Bumps and Lead Free Solder," 2000 IEEE Electronic Components and Technology Conference, pages 1111-1117.

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	BF	Tran, S.K.; Questad, D.L.; Sammakia, B.G. "Adhesion Issues in Flip-Chip on Organic Modules," 1998 InterSociety Conference on Thermal Phenomena, pages 263-268.
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	BI	www.flipchips.com/tutorial27.html "Flipchips: Tutorial 27, Shaping Gold Stud Bumps" Pages 1-8.
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